

THERMAL INTERFACE

Abstract

A thermal interface in accordance with the invention comprises a carrier having opposed surfaces, a layer of a phase-change material on one of the surfaces of the carrier, and a layer of a pliable, thermal compound on the other of the surfaces of the carrier. Also disclosed is a thermal interface product that additionally comprises a removable, protective covering overlying the pliable, thermal compound layer.

There is also provided an assembly comprising a substrate, an electronic component mounted on the substrate, a heat sink, and a thermal interface interposed between a surface of the electronic component and a surface of the heat sink for transferring heat generated by the electronic component to the heat sink, the surfaces of the heat sink and the electronic component being in confronting relationship. The thermal interface comprises a carrier having opposed surfaces, a layer of a phase-change material interposed between one of the surfaces of the carrier and one of the confronting surfaces of the heat sink and the electronic component, and a layer of a pliable, thermal compound interposed between the other surface of the carrier and the other one of the confronting surfaces.